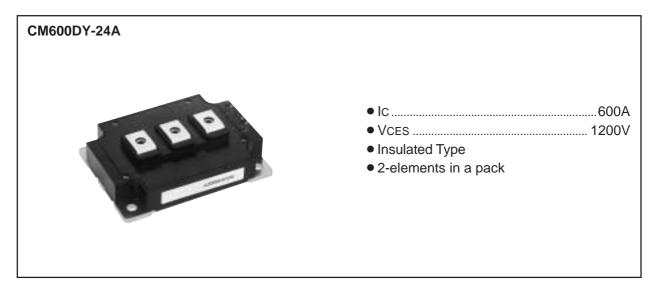
MITSUBISHI IGBT MODULES

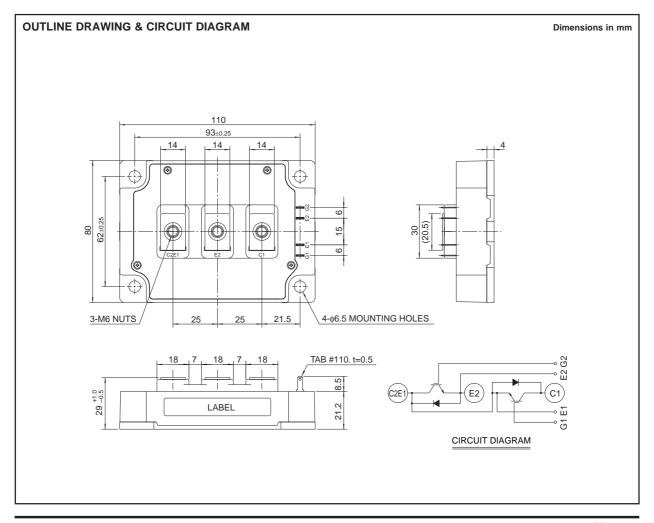
CM600DY-24A

HIGH POWER SWITCHING USE



APPLICATION

AC drive inverters & Servo controls, etc



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ABSOLUTE MAXIMUM RATINGS (Tj = 25°C)

Symbol	Parameter	Conditions		Ratings	Unit	
VCES	Collector-emitter voltage	G-E Short		1200	V	
VGES	Gate-emitter voltage	C-E Short		±20	V	
Ic	Collector current	DC, $Tc = 78^{\circ}C^{*1}$		600	A	
Ісм	Collector current	Pulse	(Note 2)	1200	A	
IE (Note 1)	Emitter current			600	Α	
IEM (Note 1)	Emitter current	Pulse	(Note 2)	1200		
PC (Note 3)	Maximum collector dissipation	$Tc = 25^{\circ}C^{*1}$		3670	W	
Tj	Junction temperature			-40 ~ + 150	°C	
Tstg	Storage temperature			− 40 ~ + 125	°C	
Viso	Isolation voltage	Main terminal to base plate, AC 1 min.		2500	V	
_	Torque etropath	Main terminal M6 Mounting holes M6		3.5 ~ 4.5	N • m	
_	Torque strength			3.5 ~ 4.5		
_	Weight	Typical value		580	g	

ELECTRICAL CHARACTERISTICS (Tj = 25°C)

Symbol	Parameter	Test conditions		Limits		
				Тур.	Max.	Unit
ICES	Collector cutoff current	VCE = VCES, VGE = 0V			1	mA
VGE(th)	Gate-emitter threshold voltage	IC = 60mA, VCE = 10V	6	7	8	V
IGES	Gate leakage current	VGE = VGES, VCE = 0V	_	_	0.5	μΑ
VCE(sat)	Collector-emitter saturation	Tj = 25°C	_	2.1	3.0	V
	voltage	$T_j = 125^{\circ}C$ IC = 600A, VGE = 15V	_	2.4	_	
Cies	Input capacitance	\\ 40\\	_	_	94	nF
Coes	Output capacitance	VCE = 10V	_	_	8	
Cres	Reverse transfer capacitance	VGE = 0V	_	_	1.8	
QG	Total gate charge	Vcc = 600V, Ic = 600A, VGE = 15V	_	2700	_	nC
td(on)	Turn-on delay time		_	_	660	
tr	Turn-on rise time	Vcc = 600V, Ic = 600A	_	_	190	ns
td(off)	Turn-off delay time	VGE1 = VGE2 = 15V	_	_	700	
tf	Turn-off fall time	RG = 0.52Ω , Inductive load switching operation	_	_	350	
trr (Note 1)	Reverse recovery time	IE = 600A	_	_	250	ns
Qrr (Note 1)	Reverse recovery charge		_	19	_	μС
VEC(Note 1)	Emitter-collector voltage	IE = 600A, VGE = 0V	_	_	3.8	V
Rth(j-c)Q	Thermal resistance	IGBT part (1/2 module)*1	_	_	0.034	
Rth(j-c)R	Thermal resistance	FWDi part (1/2 module)*1		_	0.062	°C/W
Rth(c-f)	Contact thermal resistance	Case to fin, Thermal compound Applied (1/2 module)*2	_	0.018	_	
RG	External gate resistance		0.52	_	7.8	Ω

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^{*1 :} Tc, Tf measured point is just under the chips.
*2 : Typical value is measured by using Shin-etsu Silicone "G-746".

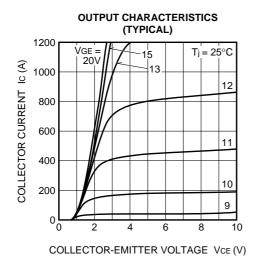
Note 1. IE, VEC, trr & Qrr represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWDi).

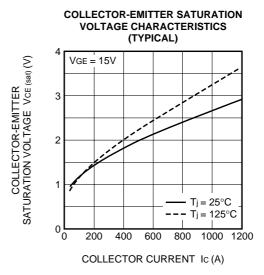
^{2.} Pulse width and repetition rate should be such that the device junction temp. (Tj) does not exceed Tjmax rating.

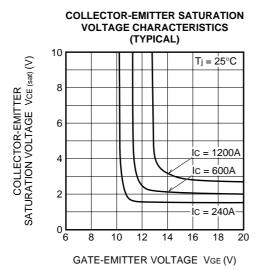
3. Junction temperature (Tj) should not increase beyond 150°C.

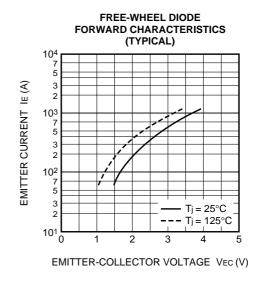
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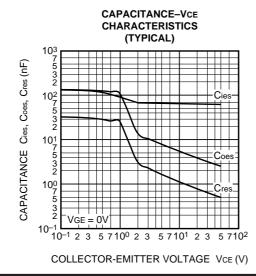
PERFORMANCE CURVES

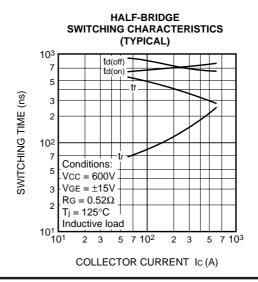








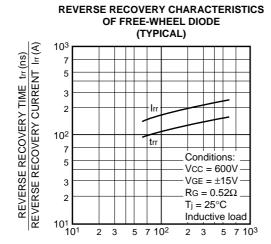




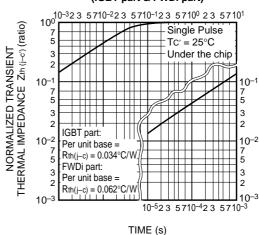
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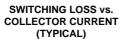


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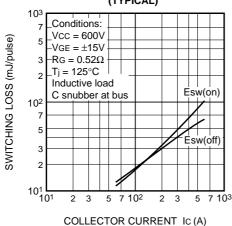


TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (IGBT part & FWDi part)

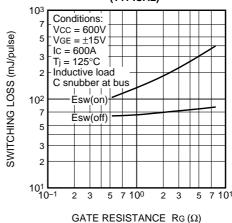




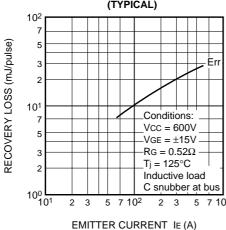
EMITTER CURRENT IE (A)



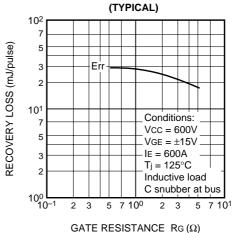
SWITCHING LOSS vs. GATE RESISTANCE (TYPICAL)



RECOVERY LOSS vs. le (TYPICAL)



RECOVERY LOSS vs. GATE RESISTANCE (TYPICAL)



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HIGH POWER SWITCHING USE

